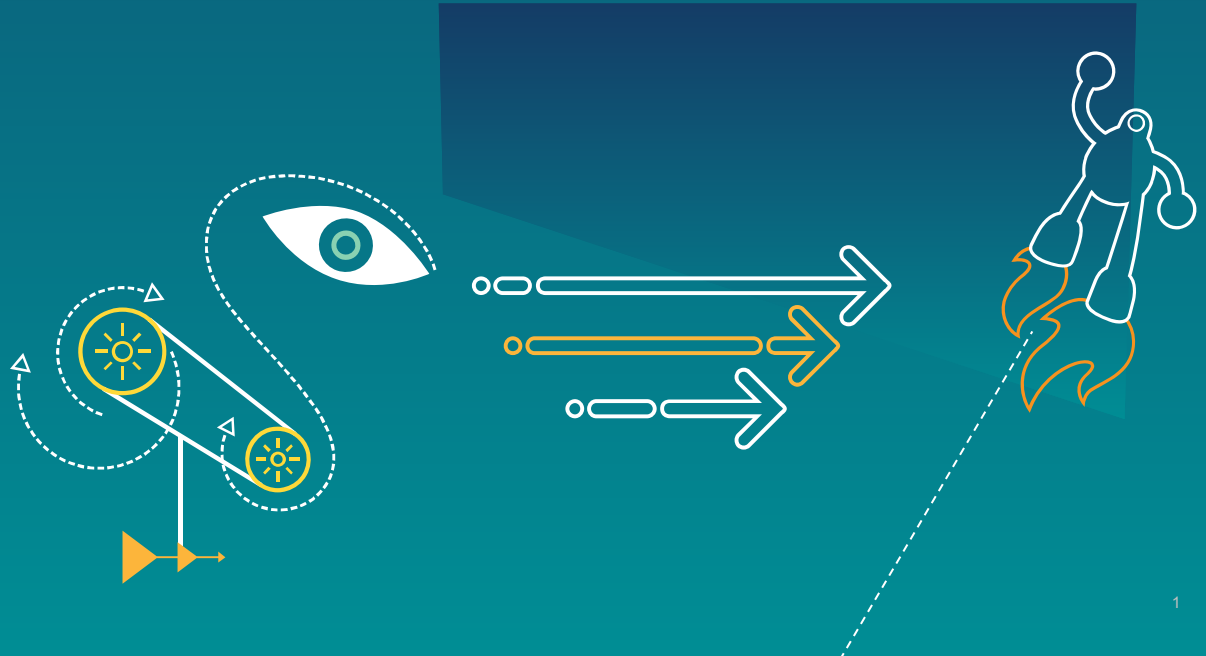


Speaker name
Job title, date, legal entity

layout feedback




April 19th

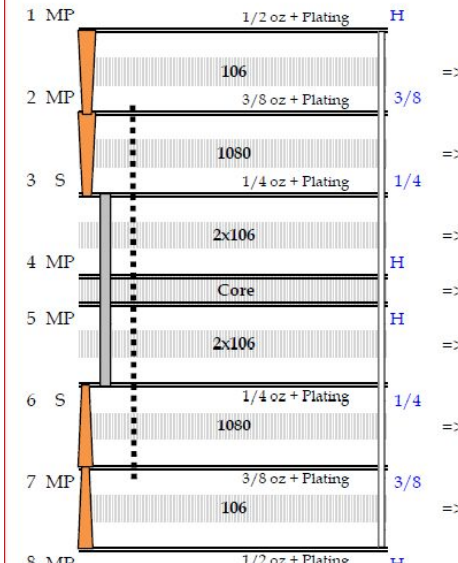


Stackup change

We switched to different PWB manufacturer.

Need to update all the control impedance traces in all the layers

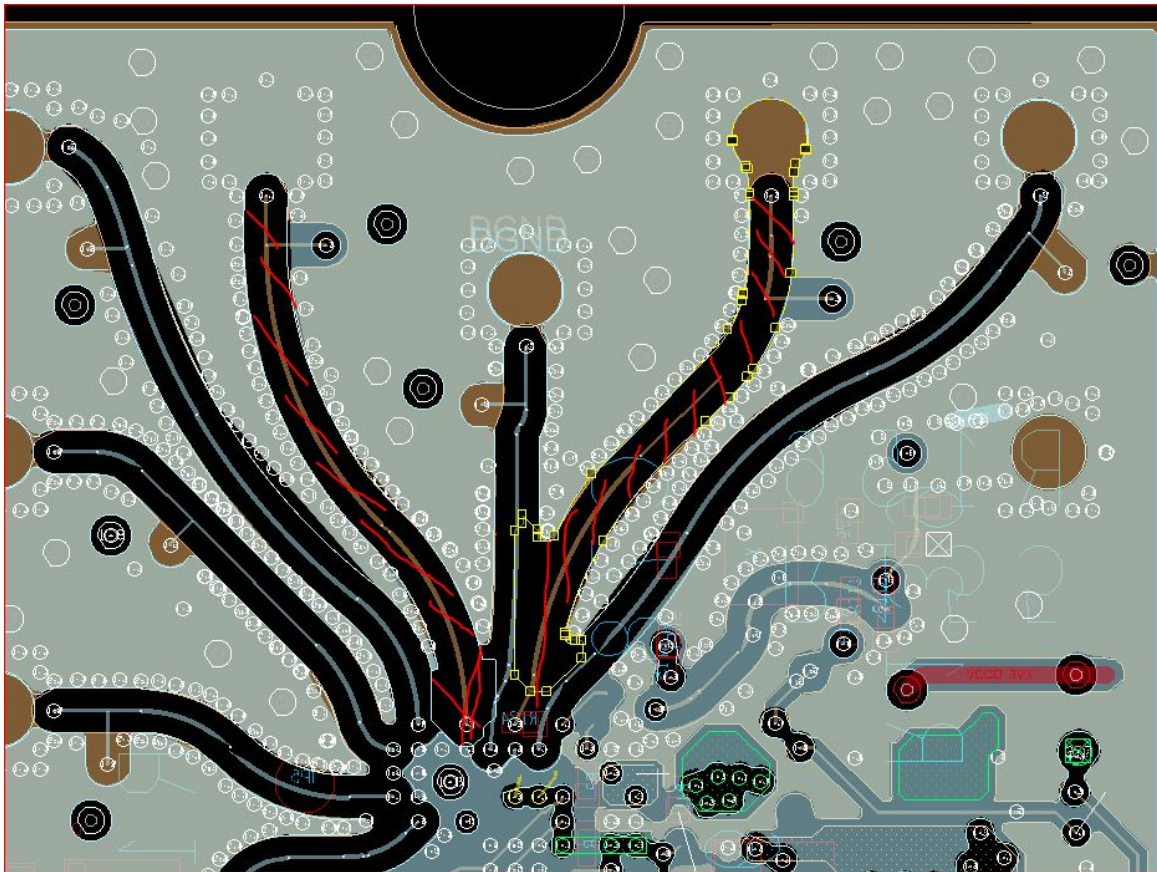
| Waivers - Customer approval of stackup includes approval of: | | Notes / Comments: | | | | | | | | | | | | | | | | | |
|--|----------------|--|-------------|--------------------|---------------------------|----------|------------|------------|---------------------|--------------------|--------------|---------|----------------|----------|------------|------------|------------|--------|----|
| | | 1- Please include approved stackup with final data set. | | | | | | | | | | | | | | | | | |
| | |  Stacked micro vias: Layers 1-2, 2-3, 7-6 and 8-7 to be copper filled  Buried vias: Layers 3-6 will be non conductive epoxy filled.  Indicates a Dummy Sub. (TTM's internal use only) | | | | | | | | | | | | | | | | | |
| Layer # | Nominal Thick. | Tolerance | LYR # | Single Ended Model | | | | | LYR # | Differential Model | | | | | | K | | | |
| | | | | Org. L/W | A/W L/W | Fin. L/W | Ref. Plane | Calc. Imp. | | Org. L/W | Org. space | A/W L/W | A/W space | Fin. L/W | Fin. space | Ref. Plane | Calc. Imp. | Factor | |
| | | | | | | | | | | | | | | | | Zs | Ks | ZD | KD |
| 1 MP | 43.18 | | 1 | 77 | | 77 | 2 | 50 | 1 | 72 | 250 | | | 72 | 250 | 2 | 100 | | |
| | 53.34 | | | | | | | | 1 | 100 | 180 | | | 100 | 180 | 2 | 85 | | |
| 2 MP | 16.51 | | | | | | | | | | | | | | | | | | |
| | 60.96 | | | | | | | | | | | | | | | | | | |
| 3 S | 26.67 | | 3 | 70 | | 70 | 2 & 4 | 50 | 3 | 70 | 250 | | | 70 | 250 | 2 & 4 | 100 | | |
| | 113.03 | | | | | | | | 3 | 95 | 180 | | | 95 | 180 | 2 & 4 | 85 | | |
| 4 MP | 16.51 | | | | | | | | | | | | | | | | | | |
| | 101.60 | | | | | | | | | | | | | | | | | | |
| 5 MP | 16.51 | | | | | | | | | | | | | | | | | | |
| | 113.03 | | | | | | | | | | | | | | | | | | |
| 6 S | 26.67 | | 6 | 70 | | 70 | 5 & 7 | 50 | 6 | 70 | 250 | | | 70 | 250 | 5 & 7 | 100 | | |
| | 60.96 | | | | | | | | 6 | 95 | 180 | | | 95 | 180 | 5 & 7 | 85 | | |
| 7 MP | 16.51 | | | | | | | | | | | | | | | | | | |
| | 53.34 | | | | | | | | | | | | | | | | | | |
| 8 MP | 43.18 | | 8 | 77 | | 77 | 7 | 50 | 8 | 72 | 250 | | | 72 | 250 | 7 | 100 | | |
| Thickness After plating | | | 762.00 | | not including solder mask | | | | Units | | Um | | | | | | | | |
| Target Thickness | | | 0.8 ± 0.100 | | over Plating | | | | Impedance Tolerance | | (SE) +/- 10% | | (DIFF) +/- 15% | | | | | | |



XIF Trace on Layer 3 – fill Layer 2

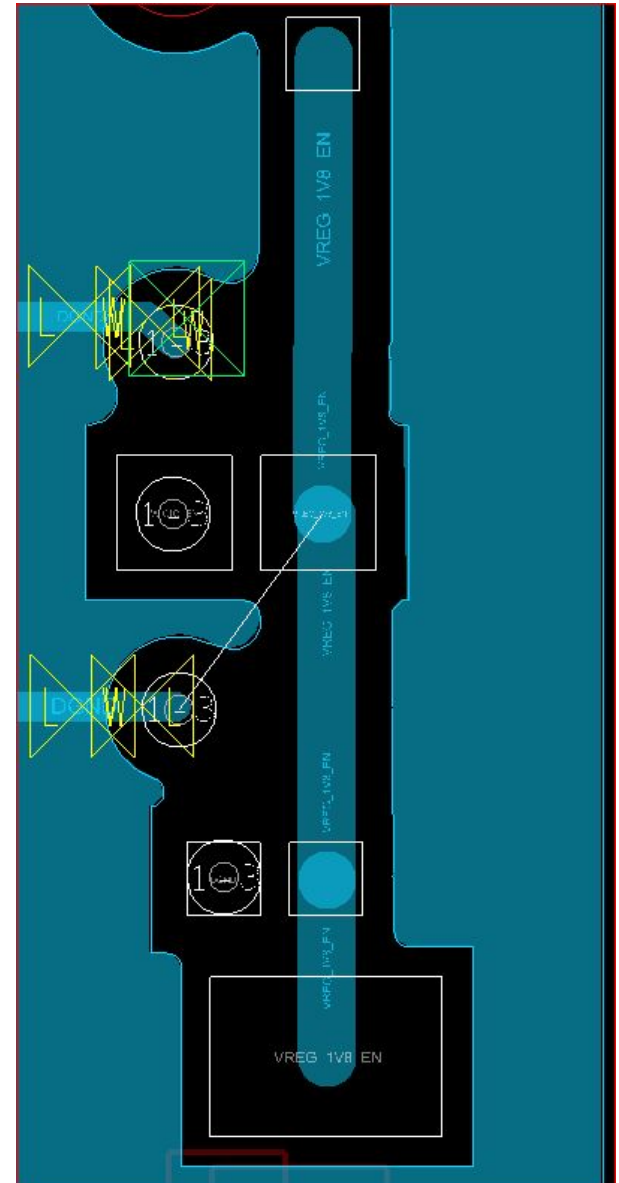
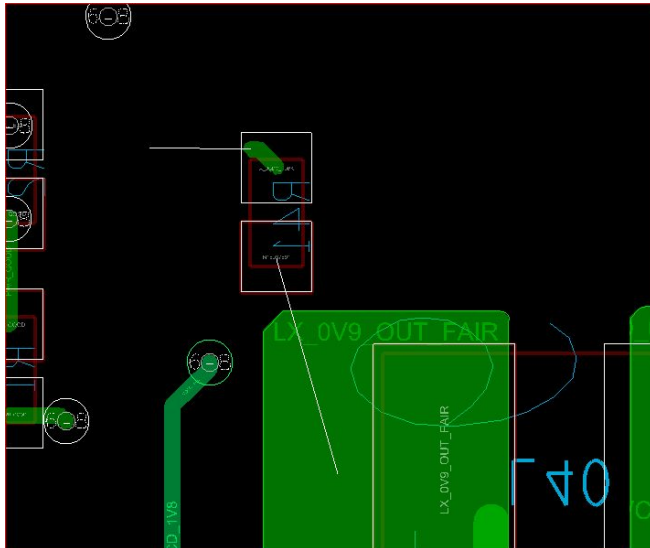
Route on L3 with L2 full reference above (ref layers L2 and L4)

Ned stackup allow this new routing



Netlist change

Fix open nets – I removed several components



Silk screen

Make the bottom side label smaller to fit the

